



Project HyPOT

- Glass Substrate Enables Low HF & Optical Losses
- Lens Design for High Coupling Tolerances & Easy Manufacturing
- Monolithically Integrated Fresnel or Additive Polymer Lenses
- Hermetically Filled Through-Glass Vias in $\text{\O}200$ mm Glass Wafer
- 12ch High-Frequency Optimization for >25 Gbit/s/channel
- Flip-Chip Assembly for Easy Thermal Packaging